

Specifications

Insulation Resistance: 1,000M Ω min. at 500V DC
 Dielectric Withstanding Voltage: 700V AC for 1 minute
 Contact Resistance: 30m Ω max. at 10mA/20mV max.
 Current Rating: 1A max.
 Operating Temperature Range: -40°C to +150°C
 Mating Cycles: 10,000 insertions min.

Materials and Finish

Housing: Polyethersulphone (PES), Polyetherimide (PEI)
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Features

- ◇ Card thickness 1.27mm
- ◇ Kelvin type contact which utilizes both sides of the contact system
- ◇ Easy insertion and extraction by latch

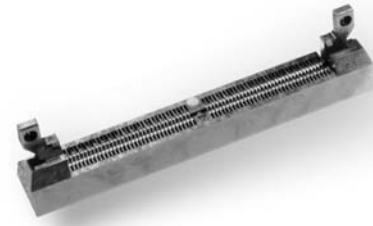
Part Number (Details)

IC-176 - 4 - MF

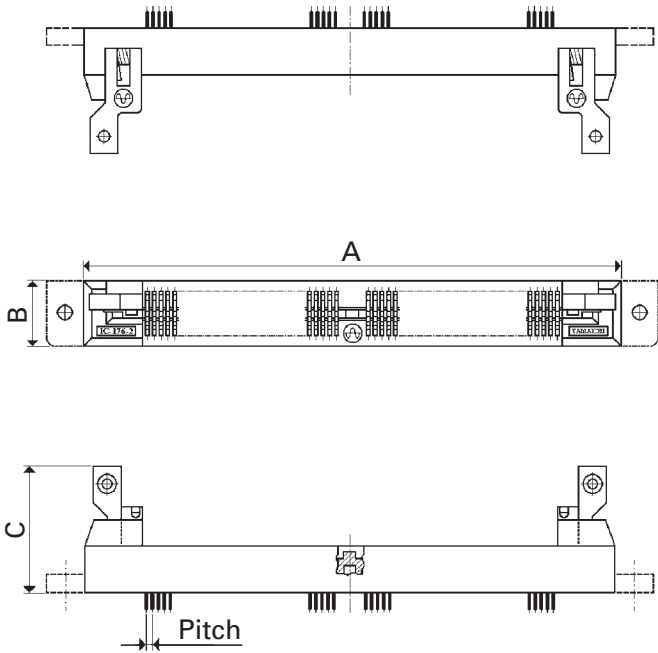
Series No.

Design Number

MF = Flanged
 Unmarked = Not Flanged

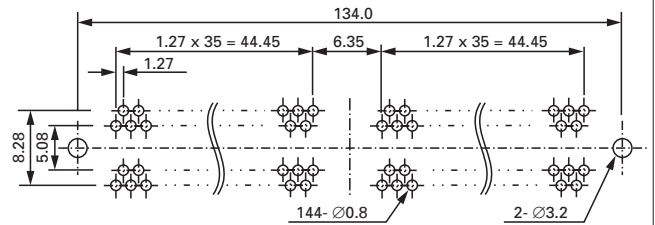


Outline Socket Dimensions

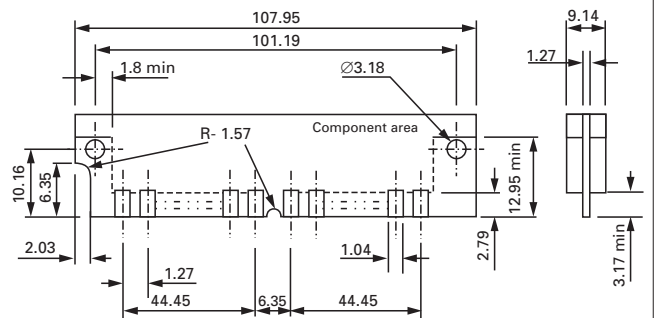


IC-176-2-***

Recommended PC Board Layout Top View from Socket



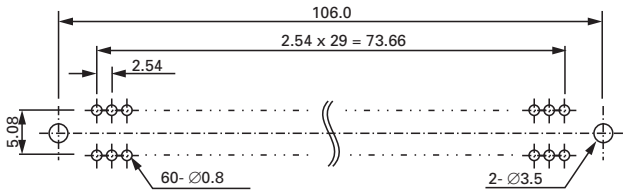
Matching IC Dimensions



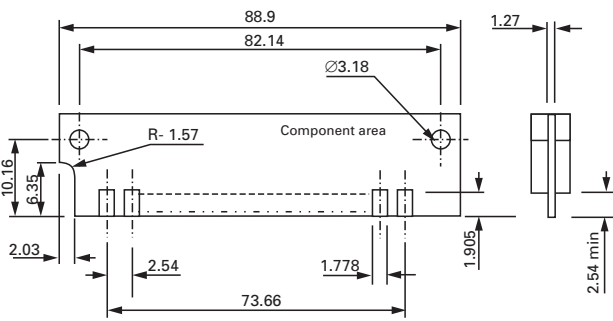
Part Number	Pin Count	Pitch	A	B	C
IC-176-4-***	30	2.54	100.0	9.0	30.0
IC-176-6-***	35	2.54	115.0	9.0	30.0
IC-176-8-***	64	1.27	115.0	15.0	30.0
IC-176-2-***	72	1.27	125.0	15.0	30.0
IC-176-10-***	100	1.27	161.4	17.0	30.0

IC-176-4-**

Recommended PC Board Layout Top View from Socket

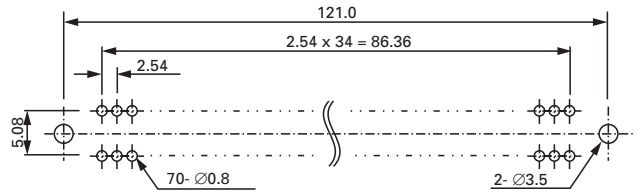


Matching IC Dimensions

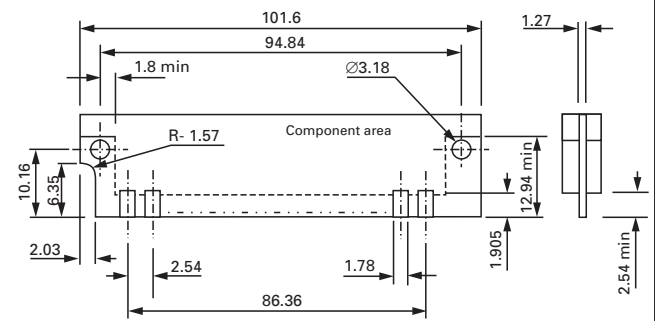


IC-176-6-**

Recommended PC Board Layout Top View from Socket

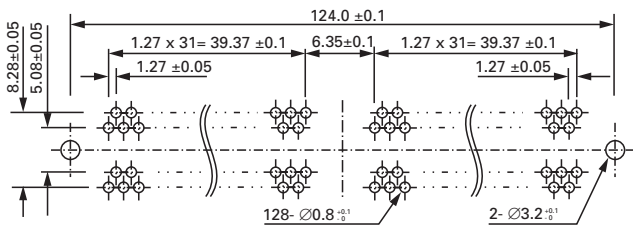


Matching IC Dimensions



IC-176-8-**

Recommended PC Board Layout Top View from Socket



IC-176-10-**

Recommended PC Board Layout Top View from Socket

